

Product / Package Information

Package	SOIC_IC
Body Size	300 mils
Lead Count	8
Terminal Finish	100 Sn
MS Number	MS011060B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.45 E-01	86.9	869100	57.70		577024
Thermosets	Epoxy & Phenol Resin	Proprietary	2.14 E-02	12.8	127800	8.49		84851
Other inorganic materials	Carbon black	1333-86-4	5.19 E-04	0.3	3100	0.21		2058
Subtotal			1.67 E-01	100	1000000	66.39		663933

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	7.63 E-02	97.5	975000	30.29		302906
Copper & its alloys	Iron	7439-89-6	1.84 E-03	2.35	23500	0.73		7301
Copper & its alloys	Zinc	7440-66-6	9.39 E-05	0.12	1200	0.04		373
Copper & its alloys	Phosphorus	7723-14-0	2.35 E-05	0.03	300	0.01		93
Subtotal			7.83 E-02	100.00	1000000	31.07		310673

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.91 E-04	100.0	1000000	0.31		3138

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.82 E-03	100.0	1000000	1.12		11173

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.77 E-04	99.0	990000	0.11		1097
Precious metals	Palladium	7440-05-3	2.79 E-06	1.0	10000	0.001		11
Subtotal			2.79 E-04	100.0	1000000	0.11		1108

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.23 E-03	100.0	1000000	0.88		8845

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.19 E-04	77.00	770000	0.09		871
Other organic materials	Acrylic resin	Proprietary	1.99 E-05	7.00	70000	0.01		79
Other organic materials	Acrylate	Proprietary	1.57 E-05	5.50	55000	0.01		62
Other organic materials	Polybutadiene derivative	Proprietary	1.28 E-05	4.50	45000	0.01		51
Other organic materials	Epoxy resin	Proprietary	7.12 E-06	2.50	25000	0.003		28
Other organic materials	Butadiene Copolymer	Proprietary	4.27 E-06	1.50	15000	0.002		17
Others	Additive	Proprietary	4.27 E-06	1.50	15000	0.002		17
Others	Peroxide	Proprietary	1.42 E-06	0.50	5000	0.001		6
Subtotal			2.85 E-04	100.00	1000000	0.11		1131

Package Totals	Weight (g)	Percentage (%)	PPM
	2.52 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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